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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **SUNOHARA, Masahiro, et al.**

Group Art Unit: **2826**

Serial No.: **10/720,514**

Examiner: **Alexander O. William**

Filed: **November 25, 2003**

P.T.O. Confirmation No.: 5140

**FOR: ELECTRONIC PARTS PACKAGING STRUCTURE HAVING MUTUALLY
CONNECTED ELECTRONIC PARTS THAT ARE BURIED IN AN INSULATING
FILM (as amended)**

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

October 15, 2004

Sir:

In response to the Office Action dated **August 2, 2004**, please amend the above-identified application as follows:

Amendments to the Title are shown on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 9 of this paper.

U.S. Patent Application Serial No. 10/720,514
Amendment filed October 15, 2004
Reply to OA dated August 2, 2004

AMENDMENTS TO THE TITLE:

Amend the title to read as follows:

ELECTRONIC PARTS PACKAGING STRUCTURE ~~AND METHOD OF~~
~~MANUFACTURING THE SAME~~ HAVING MUTUALLY CONNECTED ELECTRONIC
PARTS THAT ARE BURIED IN AN INSULATING FILM